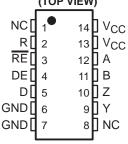
- High-Speed Low-Power LinBICMOS™ Circuitry Designed for Signaling Rates[†] of up to 30 Mbps
- Bus-Pin ESD Protection Exceeds 12 kV HBM
- Very Low Disabled Supply-Current Requirements . . . 700 μA Maximum
- Designed for High-Speed Multipoint Data Transmission Over Long Cables
- Common-Mode Voltage Range of -7 V to 12 V
- Low Supply Current . . . 15 mA Max
- Compatible With ANSI Standard TIA/EIA-485-A and ISO 8482:1987(E)
- Positive and Negative Output Current Limiting
- Driver Thermal Shutdown Protection

description

The SN65LBC180A and SN75LBC180A differential driver and receiver pairs are monolithic integrated circuits designed for bidirectional data communication over long cables that take on the characteristics of transmission lines. They are balanced, or differential, voltage mode devices that are compatible with ANSI standard TIA/EIA-485-A and ISO 8482:1987(E). The A version offers improved switching performance over its predecessors without sacrificing significantly more power.

SN65LBC180AD (Marked as BL180A) SN65LBC180AN (Marked as 65LBC180A) SN75LBC180AD (Marked as LB180A) SN75LBC180AN (Marked as 75LBC180A) (TOP VIEW)

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NC-No internal connection

Function Tables

	BRIVER	
INPUT	ENABLE	OUTPUTS
D	DE	ΥZ
Н	Н	H L
L	Н	LH
Х	L	ZZ
Open	Н	H L

RECEIVER

DIFFERENTIAL INPUTS A-B	ENABLE RE	OUTPUT R
V _{ID} ≥ 0.2 V	L	Н
–0.2 V < V _{ID} < 0.2 V	L	?
$V_{ID} \leq -0.2 V$	L	L
Х	Н	Z
Open circuit	L	Н

H = high level, L = low level, ? = indeterminate, X = irrelevant, Z = high impedance (off)

These devices combine a differential line driver and differential input line receiver and operate from a single 5-V power supply. The driver differential outputs and the receiver differential inputs are connected to separate terminals for full-duplex operation and are designed to present minimum loading to the bus when powered off ($V_{CC} = 0$). These parts feature wide positive and negative common-mode voltage ranges, making them suitable for point-to-point or multipoint data bus applications. The devices also provide positive and negative current limiting for protection from line fault conditions. The SN65LBC180A is characterized for operation from -40° C to 85° C, and the SN75LBC180A is characterized for operation from 0° C to 70° C.



Please be aware that an important notice concerning availability, standard warranty, and use in critical applications of Texas Instruments semiconductor products and disclaimers thereto appears at the end of this data sheet.

[†] Signaling rate by TIA/EIA-485-A definition restrict transition times to 30% of the bit duration, and much higher signaling rates may be achieved without this requirement as displayed in the *TYPICAL CHARACTERISTICS* of this device.

LinBiCMOS is a trademark of Texas Instruments.

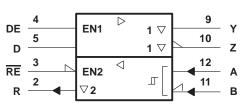
PRODUCTION DATA information is current as of publication date. Products conform to specifications per the terms of Texas Instruments standard warranty. Production processing does not necessarily include testing of all parameters.

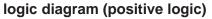


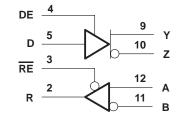
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logic symbol[†]







[†] This symbol is in accordance with ANSI/IEEE Std 91-1984 and IEC Publication 617-12.

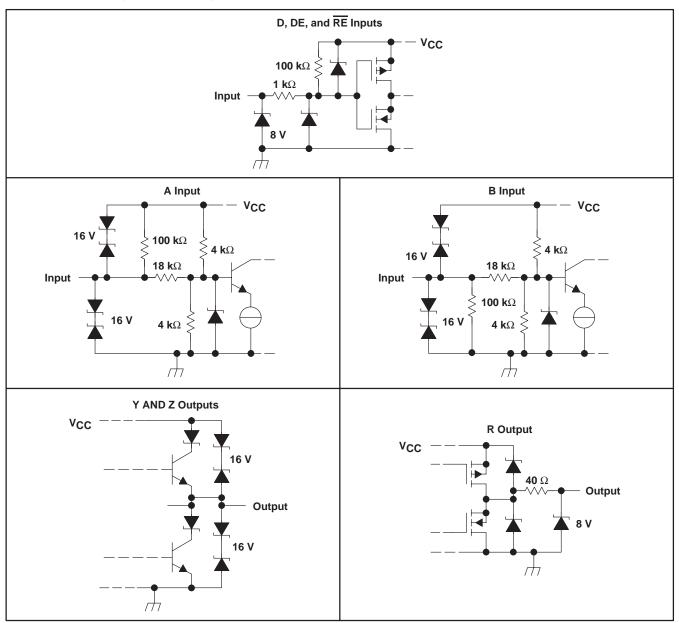
	PACKAGE				
TA	SMALL OUTLINE [†] (D)	PLASTIC DUAL-IN-LINE (N)			
0°C to 70°C	SN75LBC180AD	SN75LBC180AN			
-40°C to 85°C	SN65LBC180AD	SN65LBC180AN			

[†] The D package is available taped and reeled. Add an R suffix to the part number (i.e., SN65LBC180ADR).



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absolute maximum ratings[†]

Supply voltage range, V _{CC} (see Note 1)	
Voltage range at D, R, DE, RE	
Continuous total power dissipation (see Note 2)	Internally limited
Total power dissipation	See Dissipation Rating Table
Electrostatic discharge: Bus terminals and GND, Class 3, A: (see Note 3)	12 kV
Bus terminals and GND, Class 3, B: (see Note 3)	400 V
All terminals, Class 3, A:	
All terminals, Class 3, B:	400 V
Storage temperature range, T _{stg}	–65°C to 150°C
Lead temperature 1,6 mm (1/16 inch) from case for 10 seconds	

[†] Stresses beyond those listed under "absolute maximum ratings" may cause permanent damage to the device. These are stress ratings only, and functional operation of the device at these or any other conditions beyond those indicated under "recommended operating conditions" is not implied. Exposure to absolute-maximum-rated conditions for extended periods may affect device reliability.

NOTES: 1. All voltage values are with respect to GND except for differential input or output voltages.

- 2. The maximum operating junction temperature is internally limited. Use the dissipation rating table to operate below this temperature.
- 3. Tested in accordance with MIL-STD-883C, Method 3015.7

DISSIPATION RATING TABLE

PACKAGE	T _A ≤ 25°C POWER RATING	DERATING FACTOR [‡] ABOVE T _A = 25°C	T _A = 70°C POWER RATING	T _A = 85°C POWER RATING
D	950 mW	7.6 mW/°C	608 mW	494 mW
N	1150 mW	9.2 mW/°C	736 mW	598 mW
N		9.2 11/0/30	730 11100	290 1110

[‡] This is the inverse of the junction-to-ambient thermal resistance when board-mounted and with no air flow.

recommended operating conditions

		MIN	NOM	MAX	UNIT
Supply voltage, V _{CC}		4.75	5	5.25	V
High-level input voltage, VIH	D, DE, and RE	2		VCC	V
Low-level input voltage, VIL	D, DE, and RE	0		0.8	V
Differential input voltage, VID (see Note 4)		-12§		12	V
Voltage at any bus terminal (separately or common mode), VO, VI, or VIC	A, B, Y, or Z	-7		12	V
	Y or Z	-60			
High-level output current, IOH	R	-8			mA
	Y or Z			60	
Low-level output current, IOL	R			8	mA
Or wather free sighter and the T	SN65LBC180A	-40		85	
Operating free-air temperature, T _A	SN75LBC180A	0		70	°C

 $\frac{1}{2}$ The algebraic convention where the least positive (more negative) limit is designated minimum, is used in this data sheet.

NOTE 4: Differential input/output bus voltage is measured at the noninverting terminal with respect to the inverting terminal.



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	PARAMETER	TES	TEST CONDITIONS		TYP†	MAX	UNIT	
VIK	Input clamp voltage	I _I = – 18 mA		-1.5	-0.8		V	
		R _L = 54 Ω,,	SN65LBC180A	1 1.5		3		
1.17	Differential output voltage	See Figure 1	SN75LBC180A	1.1	1.5	3		
V _{OD}	magnitude	R _L = 60 Ω,,	SN65LBC180A	1	1.5	3	V	
		See Figure 2	SN75LBC180A	1.1	1.5	3		
Δ V _{OD}	Change in magnitude of differential output voltage (see Note 5)	See Figures 1 and 2		-0.2		0.2	V	
V _{OC} (SS)	Steady-state common-mode output voltage			1.8	2.4	2.8	V	
ΔV_{OC}	Change in steady-state common-mode output voltage (see Note 5)	See Figure 1				0.1	V	
IO	Output current with power off	$V_{CC} = 0,$	$V_{O} = -7 V$ to 12 V	-10		10	μΑ	
Iн	High-level input current	V _I = 2 V		-100			μΑ	
۱ _{IL}	Low-level input current	V _I = 0.8 V		-100			μA	
los	Short-circuit output current	$-7 \text{ V} \le \text{V}_0 \le 12 \text{ V}$		-250	±70	250	mA	
			Receiver disabled and driver enabled		5.5	9		
ICC	Supply current	$V_I = 0 \text{ or } V_{CC},$ No load	Receiver disabled and driver disabled		0.5	1	mA	
			Receiver enabled and driver enabled		8.5	15		

driver electrical characteristics over recommended operating conditions (unless otherwise noted)

[†] All typical values are at V_{CC} = 5 V and T_A = 25°C.

NOTE 5: $\Delta |V_{OD}|$ and $\Delta |V_{OC}|$ are the changes in the steady-state magnitude of V_{OD} and V_{OC} , respectively, that occur when the input is changed from a high level to a low level.

driver switching characteristics over recommended operating conditions (unless otherwise noted)

	PARAMETER	TEST CONDITIONS	MIN	TYP	MAX	UNIT
^t PLH	Propagation delay time, low-to-high-level output		2	6	12	ns
^t PHL	Propagation delay time, high-to-low-level output		2	6	12	ns
^t sk(p)	Pulse skew (t _{PLH} – t _{PHL})	$R_L = 54 \Omega, C_L = 50 pF,$ See Figure 3		0.3	1	ns
tr	Differential output signal rise time	Jee ligure 5	4	7.5	11	ns
t _f	Differential output signal fall time		4	7.5	11	ns
^t PZH	Propagation delay time, high-impedance-to-high-level output	$R_L = 110 \Omega$, See Figure 4		12	22	ns
^t PZL	Propagation delay time, high-impedance-to-low-level output	R_L = 110 Ω, See Figure 5		12	22	ns
^t PHZ	Propagation delay time, high-level-to-high-impedance output	R_L = 110 Ω, See Figure 4		12	22	ns
^t PLZ	Propagation delay time, low-level-to-high-impedance output	R _L = 110 Ω, See Figure 5		12	22	ns



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	PARAMETER		TEST CONDITIONS	MIN	TYP†	MAX	UNIT
V _{IT+}	Positive-going input threshold voltage	I _O = -8 mA	O = -8 mA			0.2	V
VIT-	Negative-going input threshold voltage	IO = 8 mA	I _O = 8 mA				V
V _{hys}	Hysteresis voltage (V _{IT+} - V _{IT} _)				50		mV
VIK	Enable-input clamp voltage	l _l = – 18 mA		-1.5	-0.8		V
VOH	High-level output voltage	V _{ID} = 200 mV,	I _{OH} = -8 mA	4	4.9		V
VOL	Low-level output voltage	$V_{ID} = -200 \text{ mV},$	IOT = 8 mV		0.1	0.8	V
IOZ	High-impedance-state output current	$V_{O} = 0 V$ to V_{CC}				1	μA
IIН	High-level enable-input current	V _{IH} = 2.4 V		-100			μA
۱ _{IL}	Low-level enable-input current	$V_{IL} = 0.4 V$		-100			μA
		V _I = 12 V, V _{CC} = 5 V			0.4	1	
		$V_I = 12 V,$ $V_{CC} = 0 V$			0.5	1	
1 ₁	Bus input current	$V_{I} = -7 V,$ $V_{CC} = 5 V$	Other input at 0 V	-0.8	-0.4		mA
		$V_{I} = -7 V,$ $V_{CC} = 0 V$		-0.8	-0.3		
			Receiver enabled and driver disabled		4.5	7.5	
ICC	Supply current	$V_{I} = 0 \text{ or } V_{CC},$ No load	Receiver disabled and driver disabled		0.5	1	mA
		1 to load	Receiver enabled and driver enabled		8.5	15	

receiver electrical characteristics over recommended operating conditions (unless otherwise noted)

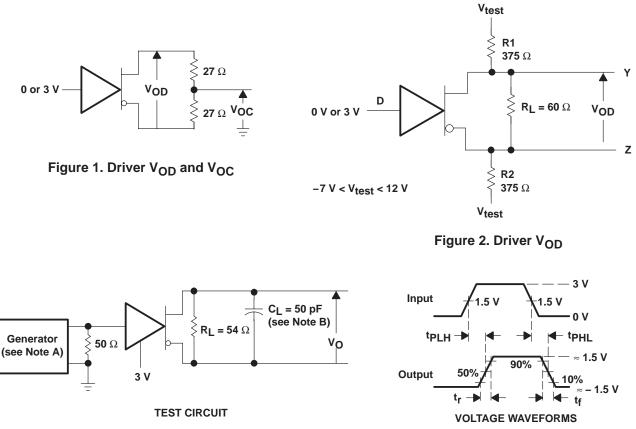
[†] All typical values are at $V_{CC} = 5$ V and $T_A = 25^{\circ}C$.

receiver switching characteristics over recommended operating conditions (unless otherwise noted)

	PARAMETER	TEST CONDI	TEST CONDITIONS			MAX	UNIT
^t PLH	Propagation delay time, low- to high-level output			7	13	20	ns
^t PHL	Propagation delay time, high- to low-level output	$V_{ID} = -1.5 \text{ V to } 1.5 \text{ V},$	See Figure 7	7	13	20	ns
^t sk(p)	Pulse skew ($ t_{PHL} - t_{PLH} $)		1 [0.5	1.5	ns
t _r	Output signal rise time				2.1	3.3	ns
t _f	Output signal fall time	See Figure 7		2.1	3.3	ns	
^t PZH	Output enable time to high level				30	45	ns
t _{PZL}	Output enable time to low level				30	45	ns
^t PHZ	Output disable time from high level	C _L = 10 pF, See Figure 8			20	40	ns
^t PLZ	Output disable time from low level		1 F			40	ns



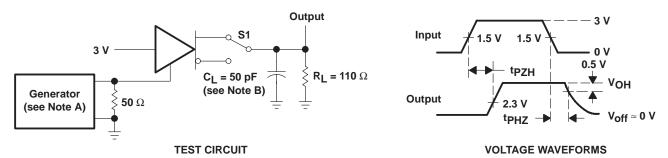
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PARAMETER MEASUREMENT INFORMATION

- NOTES: A. The input pulse is supplied by a generator having the following characteristics: PRR \leq 1 MHz, 50% duty cycle, t_f \leq 6 ns, t_f \leq 6 ns, Z_O = 50 Ω .
 - B. CL includes probe and jig capacitance.

Figure 3. Driver Test Circuit and Voltage Waveforms

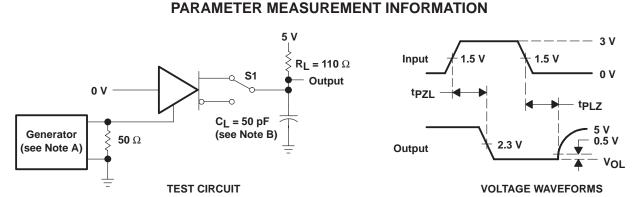


- NOTES: A. The input pulse is supplied by a generator having the following characteristics: PRR \leq 1 MHz, 50% duty cycle, t_f \leq 6 ns, t_f \leq 8 ns, t_f
 - B. CL includes probe and jig capacitance.

Figure 4. Driver Test Circuit and Voltage Waveforms



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NOTES: A. The input pulse is supplied by a generator having the following characteristics: PRR \leq 1 MHz, 50% duty cycle, t_f \leq 6 ns, t_f \leq 6 ns, Z_O = 50 Ω .

B. CL includes probe and jig capacitance.

Figure 5. Driver Test Circuit and Voltage Waveforms

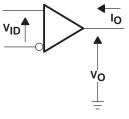
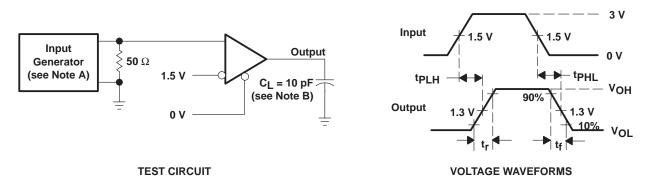


Figure 6. Receiver VOH and VOL



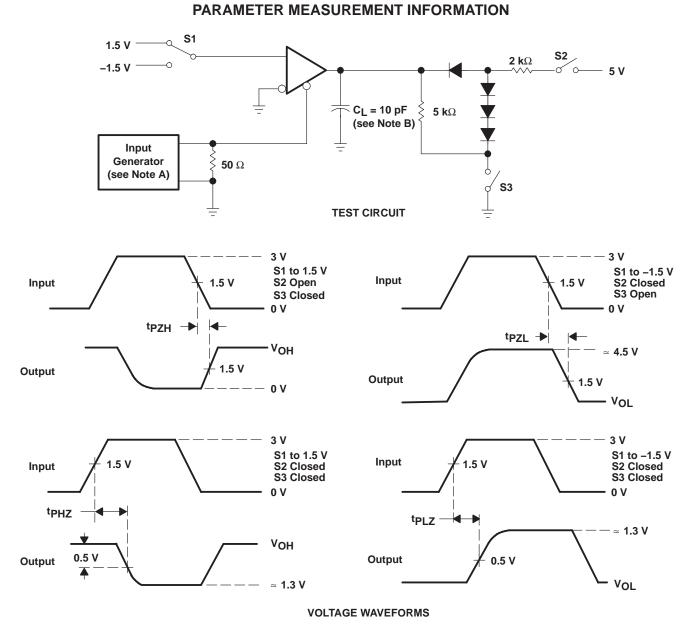
NOTES: A. The input pulse is supplied by a generator having the following characteristics: PRR \leq 1 MHz, 50% duty cycle, t_f \leq 6 ns, t_f \leq 6 ns, Z_O = 50 Ω .

B. CL includes probe and jig capacitance.

Figure 7. Receiver Test Circuit and Voltage Waveforms



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NOTES: A. The input pulse is supplied by a generator having the following characteristics: PRR \leq 1 MHz, 50% duty cycle, t_f \leq 6 ns, t_f \leq 6 ns, Z_O = 50 Ω .

B. CL includes probe and jig capacitance.

Figure 8. Receiver Output Enable and Disable Times



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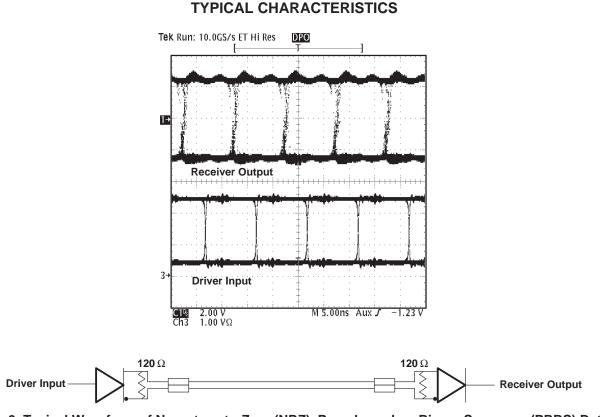
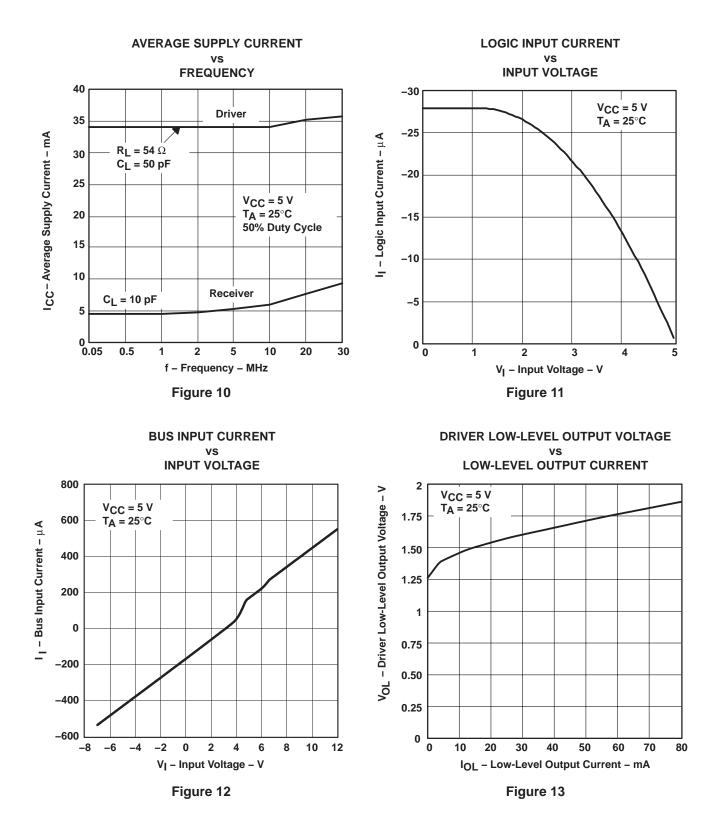


Figure 9. Typical Waveform of Nonreturn-to-Zero (NRZ), Pseudorandom Binary Sequence (PRBS) Data at 100 Mbps Through 15m, of CAT 5 Unshielded Twisted Pair (UTP) Cable

TIA/EIA-485-A defines a maximum signaling rate as that in which the transition time of the voltage transition of a logic-state change remains less than or equal to 30% of the bit length. Transition times of greater length perform quite well even though they do not meet the standard by definition.



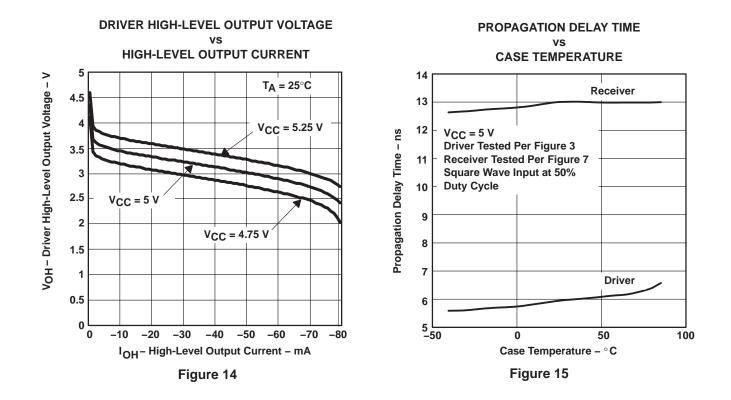
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TYPICAL CHARACTERISTICS



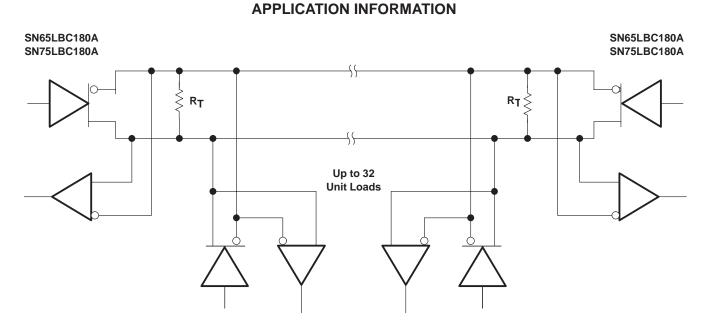
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TYPICAL CHARACTERISTICS



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NOTE A: The line should be terminated at both ends in its characteristic impedance (R_T = Z_O). Stub lengths off the main line should be kept as short as possible. One SN65LBC180A typically represents less than one unit load.

Figure 16. Typical Application Circuit



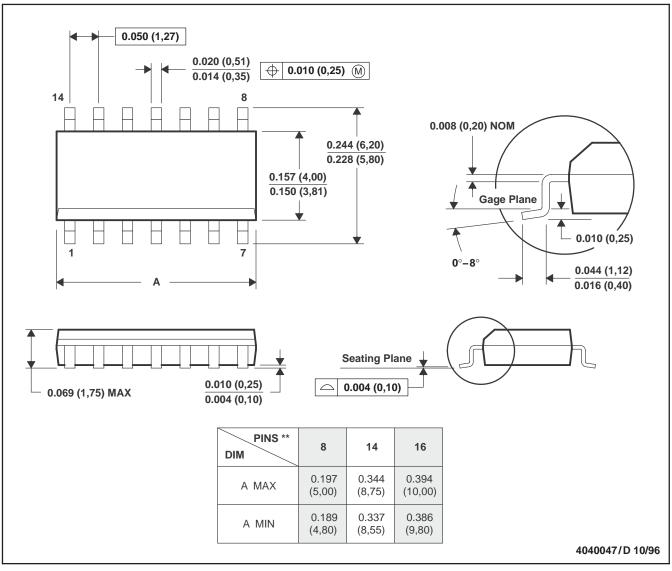
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MECHANICAL DATA

D (R-PDSO-G**)

PLASTIC SMALL-OUTLINE PACKAGE

14 PINS SHOWN



NOTES: A. All linear dimensions are in inches (millimeters).

B. This drawing is subject to change without notice.

C. Body dimensions do not include mold flash or protrusion, not to exceed 0.006 (0,15).

D. Falls within JEDEC MS-012

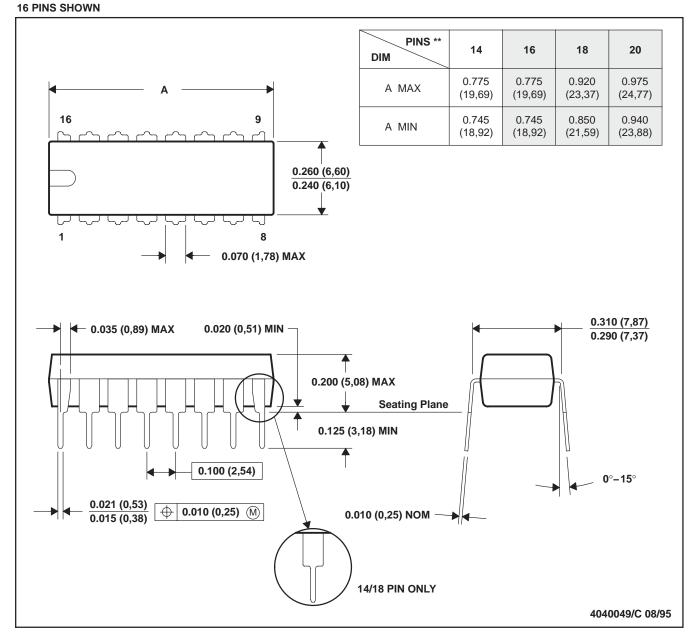


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MECHANICAL DATA

PLASTIC DUAL-IN-LINE PACKAGE

N (R-PDIP-T**)



NOTES: A. All linear dimensions are in inches (millimeters).

- B. This drawing is subject to change without notice.
- C. Falls within JEDEC MS-001 (20-pin package is shorter than MS-001).



PACKAGING INFORMATION

Orderable Device	Status ⁽¹⁾	Package Type	Package Drawing	Pins	Packag Qty	e Eco Plan ⁽²⁾	Lead/Ball Finish	MSL Peak Temp ⁽³⁾
SN65LBC180AD	ACTIVE	SOIC	D	14	50	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
SN65LBC180ADG4	ACTIVE	SOIC	D	14	50	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
SN65LBC180ADR	ACTIVE	SOIC	D	14	2500	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
SN65LBC180ADRG4	ACTIVE	SOIC	D	14	2500	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
SN65LBC180AN	ACTIVE	PDIP	Ν	14	25	Pb-Free (RoHS)	CU NIPDAU	N / A for Pkg Type
SN65LBC180ANE4	ACTIVE	PDIP	Ν	14	25	Pb-Free (RoHS)	CU NIPDAU	N / A for Pkg Type
SN75LBC180AD	ACTIVE	SOIC	D	14	50	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
SN75LBC180ADG4	ACTIVE	SOIC	D	14	50	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
SN75LBC180ADR	ACTIVE	SOIC	D	14	2500	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
SN75LBC180ADRG4	ACTIVE	SOIC	D	14	2500	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
SN75LBC180AN	ACTIVE	PDIP	Ν	14	25	Pb-Free (RoHS)	CU NIPDAU	N / A for Pkg Type
SN75LBC180ANE4	ACTIVE	PDIP	Ν	14	25	Pb-Free (RoHS)	CU NIPDAU	N / A for Pkg Type

⁽¹⁾ The marketing status values are defined as follows:

ACTIVE: Product device recommended for new designs.

LIFEBUY: TI has announced that the device will be discontinued, and a lifetime-buy period is in effect.

NRND: Not recommended for new designs. Device is in production to support existing customers, but TI does not recommend using this part in a new design.

PREVIEW: Device has been announced but is not in production. Samples may or may not be available.

OBSOLETE: TI has discontinued the production of the device.

(2) Eco Plan - The planned eco-friendly classification: Pb-Free (RoHS), Pb-Free (RoHS Exempt), or Green (RoHS & no Sb/Br) - please check http://www.ti.com/productcontent for the latest availability information and additional product content details. TBD: The Pb-Free/Green conversion plan has not been defined.

Pb-Free (RoHS): TI's terms "Lead-Free" or "Pb-Free" mean semiconductor products that are compatible with the current RoHS requirements for all 6 substances, including the requirement that lead not exceed 0.1% by weight in homogeneous materials. Where designed to be soldered at high temperatures, TI Pb-Free products are suitable for use in specified lead-free processes.

Pb-Free (RoHS Exempt): This component has a RoHS exemption for either 1) lead-based flip-chip solder bumps used between the die and package, or 2) lead-based die adhesive used between the die and leadframe. The component is otherwise considered Pb-Free (RoHS compatible) as defined above.

Green (RoHS & no Sb/Br): TI defines "Green" to mean Pb-Free (RoHS compatible), and free of Bromine (Br) and Antimony (Sb) based flame retardants (Br or Sb do not exceed 0.1% by weight in homogeneous material)

⁽³⁾ MSL, Peak Temp. -- The Moisture Sensitivity Level rating according to the JEDEC industry standard classifications, and peak solder temperature.

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PACKAGE OPTION ADDENDUM



In no event shall TI's liability arising out of such information exceed the total purchase price of the TI part(s) at issue in this document sold by TI to Customer on an annual basis.

TAPE AND REEL INFORMATION





QUADRANT ASSIGNMENTS FOR PIN 1 ORIENTATION IN TAPE

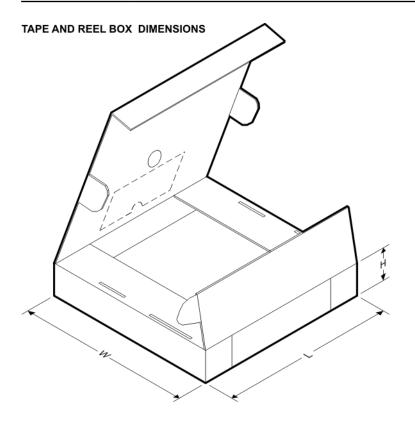


*All dimensions are nominal												
Device		Package Drawing		SPQ	Reel Diameter (mm)	Reel Width W1 (mm)	A0 (mm)	B0 (mm)	K0 (mm)	P1 (mm)	W (mm)	Pin1 Quadrant
SN65LBC180ADR	SOIC	D	14	2500	330.0	16.4	6.5	9.0	2.1	8.0	16.0	Q1
SN65LBC180ADR	SOIC	D	14	2500	330.0	16.4	6.5	9.0	2.1	8.0	16.0	Q1
SN75LBC180ADR	SOIC	D	14	2500	330.0	16.4	6.5	9.0	2.1	8.0	16.0	Q1
SN75LBC180ADR	SOIC	D	14	2500	330.0	16.4	6.5	9.0	2.1	8.0	16.0	Q1



PACKAGE MATERIALS INFORMATION

19-Mar-2008



*All dimensions are nominal

Device	Package Type	Package Drawing	Pins	SPQ	Length (mm)	Width (mm)	Height (mm)
SN65LBC180ADR	SOIC	D	14	2500	346.0	346.0	33.0
SN65LBC180ADR	SOIC	D	14	2500	333.2	345.9	28.6
SN75LBC180ADR	SOIC	D	14	2500	346.0	346.0	33.0
SN75LBC180ADR	SOIC	D	14	2500	333.2	345.9	28.6

D (R-PDSO-G14)

PLASTIC SMALL-OUTLINE PACKAGE



NOTES: A. All linear dimensions are in inches (millimeters).

- B. This drawing is subject to change without notice.
- Body length does not include mold flash, protrusions, or gate burrs. Mold flash, protrusions, or gate burrs shall not exceed .006 (0,15) per end.

Body width does not include interlead flash. Interlead flash shall not exceed .017 (0,43) per side.

E. Reference JEDEC MS-012 variation AB.



N (R-PDIP-T**)

PLASTIC DUAL-IN-LINE PACKAGE

16 PINS SHOWN



NOTES:

- A. All linear dimensions are in inches (millimeters).B. This drawing is subject to change without notice.
- Falls within JEDEC MS-001, except 18 and 20 pin minimum body length (Dim A).
- \triangle The 20 pin end lead shoulder width is a vendor option, either half or full width.



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